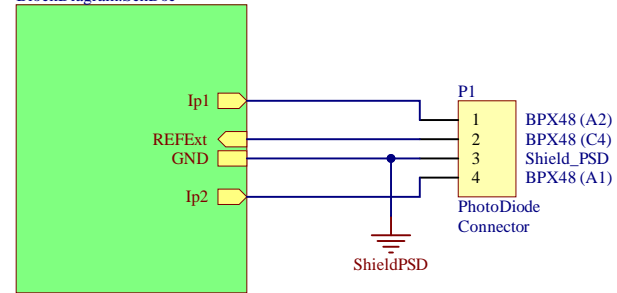


U\_BlockDiagram  
BlockDiagram.SchDoc

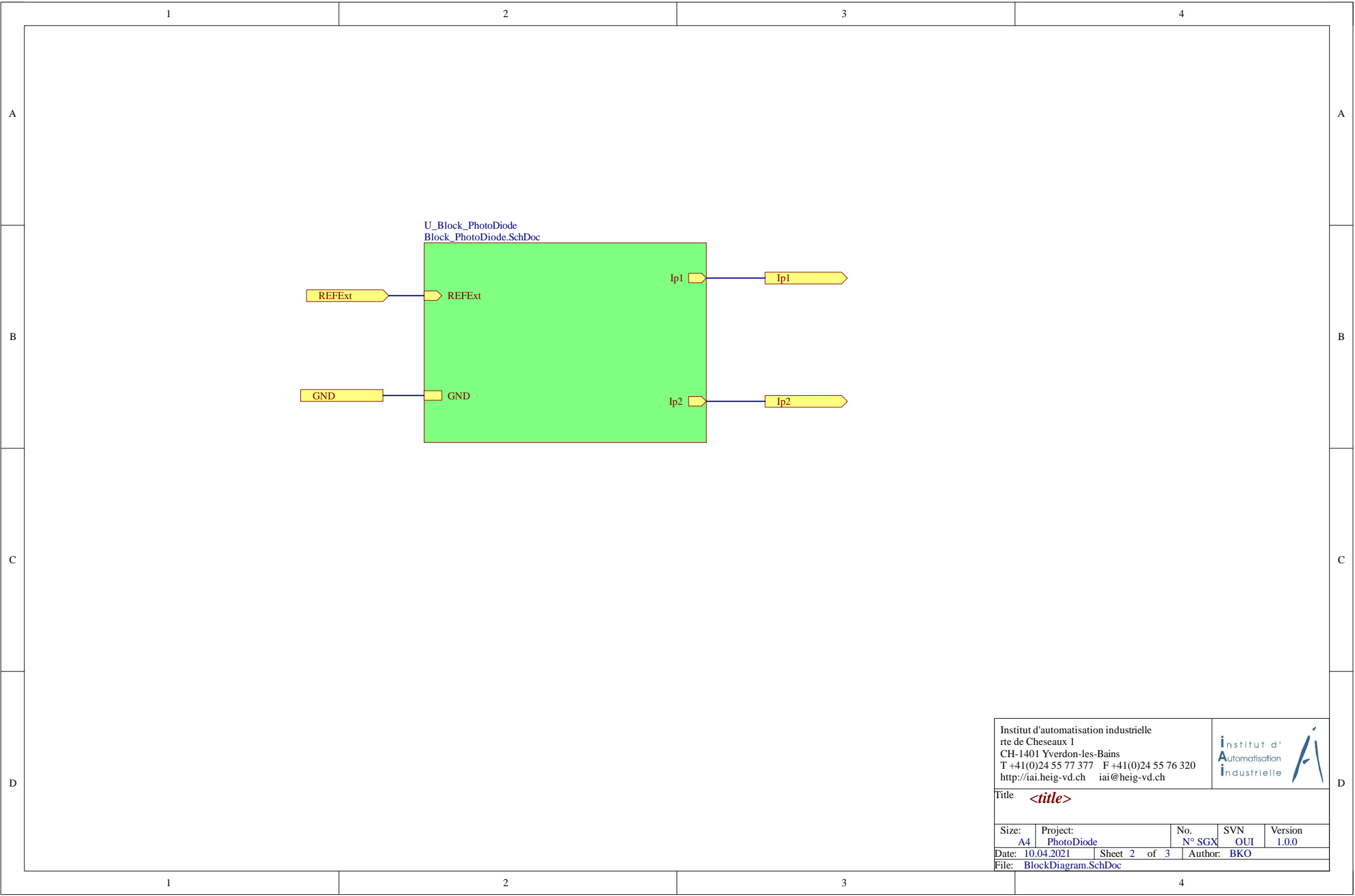


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Title *<title>*

Size: A4	Project: PhotoDiode	No. N° SGX	SVN OUI	Version 1.0.0
Date: 10.04.2021	Sheet 1 of 3	Author: BKO		
File: PhotoDiode.SchDoc				



1

2

3

4

A

A

B


B

C

C

D

D

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Title <i>&lt;title&gt;</i>				
Size: A4	Project: PhotoDiode	No. N° SGX	SVN OUI	Version 1.0.0
Date: 10.04.2021	Sheet 3 of 3	Author: BKO		
File: <a href="#">Block_PhotoDiode.SchDoc</a>				

1

2

3

4

Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	SM-001	0.025mm	4	
	Top Surface Finish	Nickel, Gold	0.020mm		
	Top Layer	CF-004	0.035mm		
1					
	Dielectric 1	PP-017	0.129mm	4,3	
	Dielectric 2	PP-017	0.129mm	4,3	
2	Int1 (GND)	CF-004	0.035mm		
	Dielectric 3	Core-039	0.711mm	4,8	
3	Int2 (PWR)	CF-004	0.035mm		
	Dielectric 4	PP-017	0.129mm	4,3	
	Dielectric 5	PP-017	0.129mm	4,3	
4					
	Bottom Layer	CF-004	0.035mm		
	Bottom Surface Finish	Nickel, Gold	0.020mm		
	Bottom Solder	SM-001	0.025mm	4	
	Bottom Overlay				

